

NI/CU DOUBLE-SIDED CONDUCTIVE FABRIC TAPE

Laird Technologies' DT06A double-sided conductive fabric tape is constructed of 1.4 mil (0.035 mm) nickel/copper metallized fabric with conductive pressure sensitive adhesives (PSA) on both sides. This reliable tape provides XYZ-axis electrical conductivity and EMI shielding performance.

DT06A is RoHS compliant and halogen free. It's good for EMI/RFI shielding to electronic devices.

FEATURES

- RoHS compliant
- Halogen-free per IEC-61249-2-21 standard
- Shielding effectiveness of >70 dB across a wide spectrum of frequencies

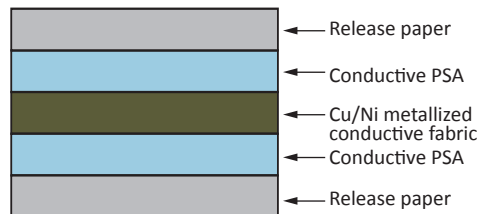
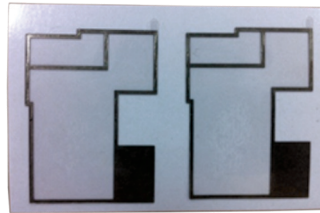
MARKETS

- Cabinet applications
- LCD and Plasma TV
- Medical equipment
- Servers
- Printers
- Laptop computers

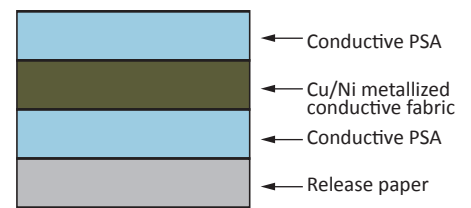


COMPOSITION OF PRODUCT

Die Cut



Roll Form



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Europe: +49.0.8031.2460.0
Asia: +86.755.2714.1166

DT06A Double-Sided Nickel/Copper Fabric Tape

Item	Unit	Typical Value	Test Method
Thickness	mm	0.06 ± 0.01	-
Peel Adhesion	Kgf / 25 mm	1.5	PSTC 101*
Shear Adhesion at R.T.	Hrs	>24	PSTC 107#
Tensile Strength	Kgf / 25 mm	8.3	
Operation Temperature	°C	0-80	-
Z-axial Resistance	Ω	<0.03	-
Thermal Resistance at 50°C/10 psi	°C-in ² /W	0.7 typical	ASTM D5470
Far-field Shielding			IEEE-299 (modified)
30 MHz to 300 MHz	dB	74	
300 MHz to 3 GHz	dB	75	
3 GHz to 18 GHz	dB	72	
Package Dimensions (Max. Width: 1000 mm)	M	W: Dimension by Customer Spec L: Standard Length of 20 M	
Shelf Life (Under 23°C/65% R.H.)		One Year	

* Test Method C, Dwell Time 30 Minutes

Contact area 25 mm by 25 mm

Values presented have been determined by standard test methods and are typical values not to be used for specification purposes.

APPLICATION TECHNIQUES

- Bond strength is dependent upon the amount of adhesive-to-surface contact developed. Firm application pressure develops better adhesive contact & thus improves bond strength.
- To obtain optimum adhesion, the bonding surfaces must be clean, dry and well unified. A typical surface cleaning solvent is isopropyl alcohol. Use proper safety precautions for handling solvents.
- Ideal tape application temperature range is 21°C to 38°C. Initial tape application to surfaces at temperatures below 10°C is not recommended because the adhesive becomes too firm to adhere readily. However, once properly applied, low temperature holding is generally satisfactory.

EMI-DS-FOF-DT06A 052915

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